Qualification Results Summary of the Wafer Level Capping of the ADXL103, ADXL203, ADXL204, ADXL212 and the ADXL213

QUALIFICATION RESULTS			
TEST	CONDITIONS	SAMPLE SIZE	RESULTS
Early Life Failure Rate (ELFR)	Mil-Std-883 Method 1015	**2000**	**Pass**
Group D Sub-Group 4	Mil-Std-883 Method 5005	**3x17**	**Pass**
Group D Sub-Group 6	Mil-Std-883 Method 5005	**3X5**	**Pass**
Highly Accelerated Stress Test (HAST)*	JEDEC *JESD22-A110*	**3x77**	**Pass**
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	**12x77**	**Pass**
Autoclave (AC)*	JEDEC *JESD22-A102*	**4x77**	**Pass**
High Temperature Storage Life (HTSL)	JEDEC *JESD22-A103*	**1x200 9x77**	**Pass**
Low Temperature Storage Life (LTS)	JEDEC JESD22-A119	**6x77**	**Pass**
Random Drop	AEC-Q100 Test G5	**3X45**	**Pass**
Solder Heat Resistance (SHR)*	*JEDEC/IPC J-STD-020*	**3x30**	**Pass**

*Preconditioned to JEDEC Std-20 MSL 3